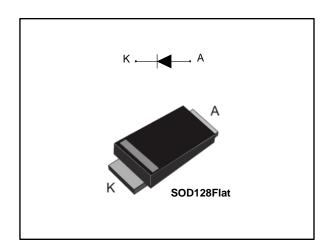


Power Schottky rectifier

Datasheet - production data



Description

This high voltage Schottky barrier rectifier device is packaged in SOD128Flat and designed for high frequency miniature switched mode power supplies and on board DC to DC converters.

Table 1: Device summary

Symbol	Value
I _{F(AV)}	3 A
V_{RRM}	60 V
T _j (max.)	175 °C
V _F (typ.)	0.49 V

Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche specification
- ECOPACK® compliant component

Characteristics STPS360

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Pa	Value	Unit	
V_{RRM}	Repetitive peak reverse voltage	Repetitive peak reverse voltage		V
I _{F(AV)}	Average forward current	T_L = 140 °C, δ = 0.5, square pulse	3	Α
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	65	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 10 \ \mu s, \ T_j = 125 \ ^{\circ}C$		140	W
T _{stg}	Storage temperature range		-65 to +175	°C
Tj	Operating junction temperature range ⁽¹⁾		-40 to +175	°C

Notes:

Table 3: Thermal parameters

Symbol	Parameter	Max. value	Unit
R _{th(j-l)}	Junction to lead	16	°C/W

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
1 (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	V _R = 60 V	-		150	μΑ
IR ^(*)		T _j = 125 °C		•	20	30	mA
	Forward voltage drop	T _j = 25 °C	I _F = 3 A	-		0.61	V
V _F ⁽²⁾		T _j = 125 °C		-	0.49	0.58	
		T _j = 25 °C	I _F = 6 A	1		0.80	
		T _j = 125 °C		ı	0.62	0.72	

Notes:

 $^{(1)}$ Pulse test: t_p = 5 ms, δ < 2%

(2) Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

 $P = 0.44 \text{ x } I_{F(AV)} + 0.047 \text{ x } I_{F^2(RMS)}$

For more information, please refer to the following application notes related to the power losses.

- AN604 (Calculation of conduction losses in a power rectifier)
- AN4021 (Calculation of reverse losses in a power diode)

 $^{^{(1)}(}dP_{tot}/dT_j) < (1/R_{th(j-a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$

STPS360 Characteristics

Characteristics (curves) 1.1

0.0

0.001

Figure 1: Average forward power dissipation versus average forward current PF(AV)(W) $\delta = 0.05$ 2.0 1.0 0.5 I_{F(AV)}(A) 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0

Figure 2: Average forward current versus ambient temperature ($\delta = 0.5$) I_{F(AV)}(A) 6 Tamb(°C) 0 0 25 75 125 175

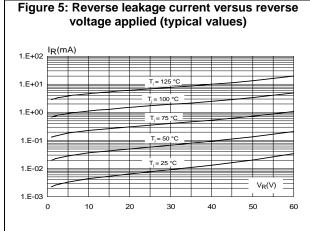
Figure 3: Normalized avalanche power derating versus pulse duration $(T_j = 125 °C)$ $\frac{P_{ARM}(t_p)}{P_{ARM}(10 \ \mu s)}$ 0.1 0.01

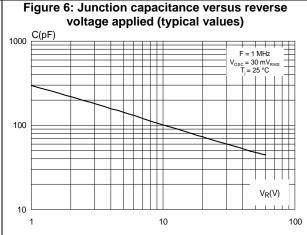
100

1000

10

Figure 4: Relative variation of thermal impedance junction to lead versus pulse duration $Z_{th(j-l)}/R_{th(j-l)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 Single pulse 0.1 t_P(s) 0.0 1.E-04 1.E-03 1.E-02 1.E-01 1.E+00 1.E+01





Characteristics STPS360

Figure 7: Forward voltage drop versus forward current (typical values) 10.00 1.00 T_j = 125 °C 0.10 0.01 0.0 0.1 0.2 0.3 0.5 0.6 0.4 0.7 8.0 0.9

versus copper surface under each lead (typical values) R_{th(j-a)}(°C/W) SOD128-Flat 150 100 Epoxy printed board FR4, e_{Cu} = 35 μm 0.5 1.0 1.5 3.0 3.5 5.0 0.0 2.0 2.5 4.0 4.5

Figure 8: Thermal resistance junction to ambient

STPS360 Package information

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Lead-free package

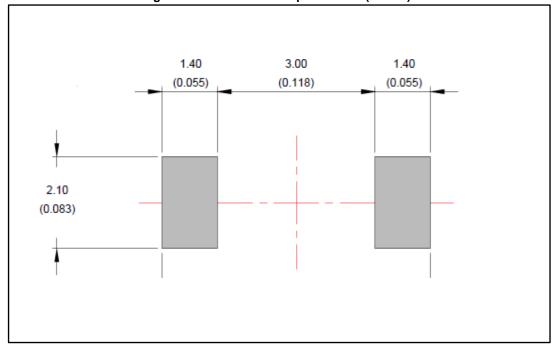
2.1 SOD128Flat package information

Figure 9: SOD128Flat package outline

Table 5: SOD128Flat package mechanical data

	Dimensions				
Ref.	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
А	0.93	1.03	0.037	0.041	
b	1.69	1.81	0.067	0.071	
С	0.10	0.22	0.004	0.009	
D	2.30	2.50	0.091	0.098	
E	4.60	4.80	0.181	0.189	
E1	3.70	3.90	0.146	0.154	
L	0.55	0.85	0.026	0.033	
L1	0.30 typ.		0.012	2 typ.	
L2	0.45 typ.		0.018	B typ.	

Figure 10: SOD128Flat footprint in mm (inches)



STPS360 Ordering information

3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS360AF	360F	SOD128Flat	26.4 mg	3000	Tape and reel

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
01-Jul-2016	1	Initial release.

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